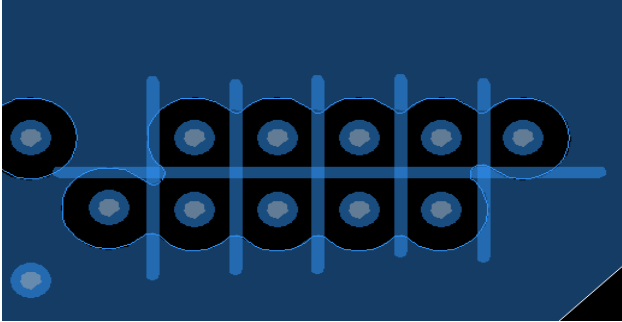
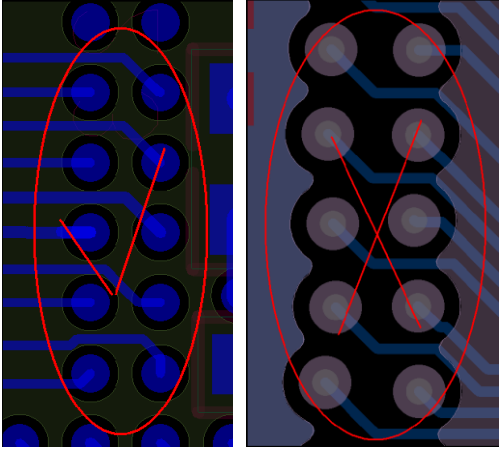


1	Stackup - Impadence -Trace Width								
	---	Stackup Structure				Impedance Requirements			
	Layer	Type	Thickness (mil)		Dk(with Sim Z0)	Impedance spec (Ohms)	Reference layer	Width/space (mil)	Sim Z0(Ohms)
		solder mask	0.5	SM	4.25				
	1	TOP	1.6	0.3oz+plating		50±10%	2	4	52.18
						90±10%	2	4.5/7.5	90.03
						100±10%	2	3.8/8.7	98.5
		prepreg	2.9		4				
	2	GND	1.2	1.0oz					
		core	27.0		4.5				
	3	VCC	1.2	1.0oz					
		prepreg	2.9		4				
	4	BOTTOM	1.6	0.3oz+plating		50±10%	3	4	52.18
						90±10%	3	4.5/7.5	90.03
						100±10%	3	3.8/8.7	98.5
		solder mask	0.5	SM	4.25				
		Board thickness:	39.4						
2	走线宽度								
	单端：外层走线线宽4mil，内层4mil。								
	差分：外层走线线宽/线距为3.7/8.8mil；内层3.7/8.8mil。								
	电源和地Fanout线宽：≥10mil。								
3	间距								
	单端：外层线与线的间距（Air Gap）≥8mil,内层≥8mil。								
	差分线：到其他网络走线间距≥12mil。								
	电源与地：到其他网络走线的间距≥12mil。								
	VREF：到其他网络走线的间距≥15mil。								
	BGA区域里：线与线4mil；线与SMD PIN 4mil；线与过孔4mil。								
4	拓扑								
	DQ：点对点								
	DQS、DQSB：点对点								
	Ax、BAx、CAS、RAS、WE、CSx、ODTx、CKEx、RST：点对点								
	CK、CKB：点对点								
5	等长								
	DQ0-7：相对于DQS0、DQSB0做等长，误差范围为≤100mil。过孔数一致。								
	DQ8-15：相对于DQS1、DQSB1做等长，误差范围为≤100mil。过孔数一致。								
	DQ16-23：相对于DQS2、DQSB2做等长，误差范围为≤100mil。过孔数一致。								
	DQ24-31：相对于DQS3、DQSB3做等长，误差范围为≤100mil。过孔数一致。								
	DQSx、DQSBx：								
	相对于CK/CKB信号做等长，误差范围为≤1000mil。								
	Ax、BAx、CAS、RAS、WE、CSx、ODTx、CKEx：								
	相对于CK/CKB信号做等长，误差范围为≤600mil。								
	DQSx与DQSBx等长，等长误差范围为≤10mil。								
	CK与CKB等长，等长误差范围为≤10mil。								

	信号线做等长时要考虑过孔长度的影响
6	电源、地平面 <p>平面比较完整，调整好过孔的位置、间距，减少对电源、地平面的破坏。平面断开处用走线连接</p>  <p>电源、地平面同时也是信号的参考层要求，不能有信号线的参考层被割断的现象</p> 
7	滤波电容： <p>对于单面布局：尽量靠近电源PIN放置，每个电容至少各一个电源过孔和地过孔。</p> <p>对于双面布局：最好能放置在电源管脚下方的PCB背面，每个电容至少各一个电源过孔和地过孔。</p> <p>不同容值的电容均匀分布。</p>

1. Declaration

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